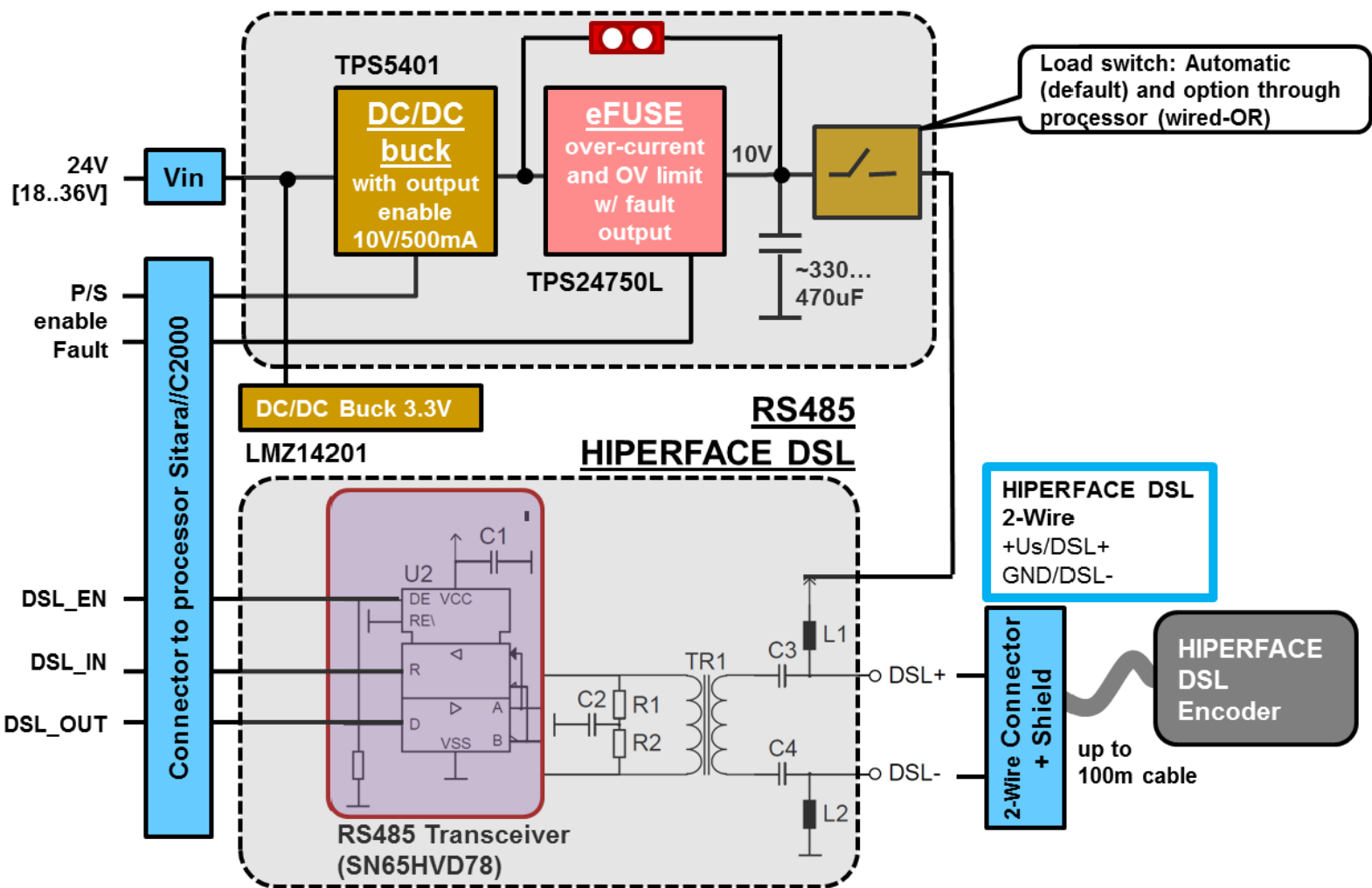
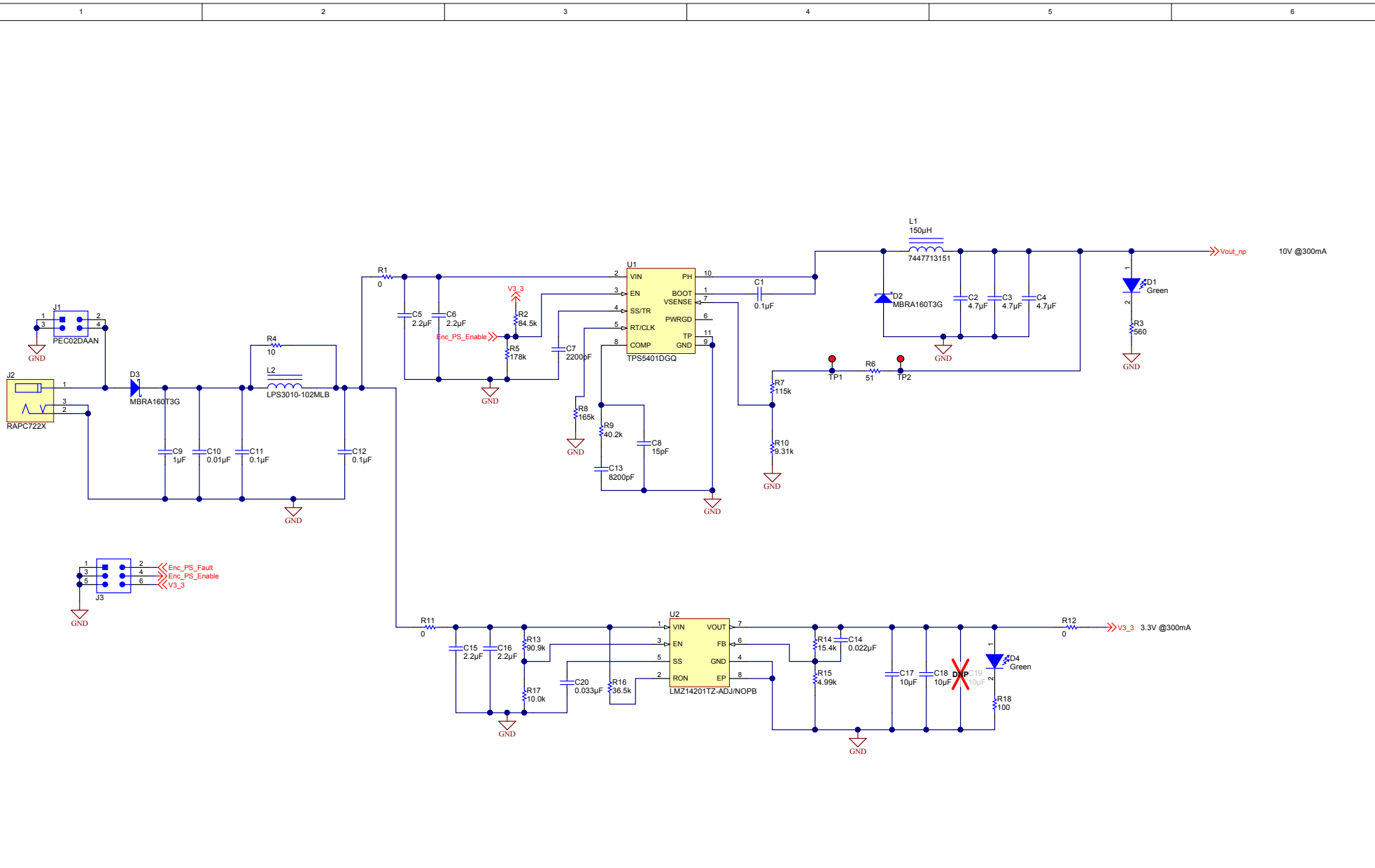


# HIPERFACE DSL Encoder Power Supply



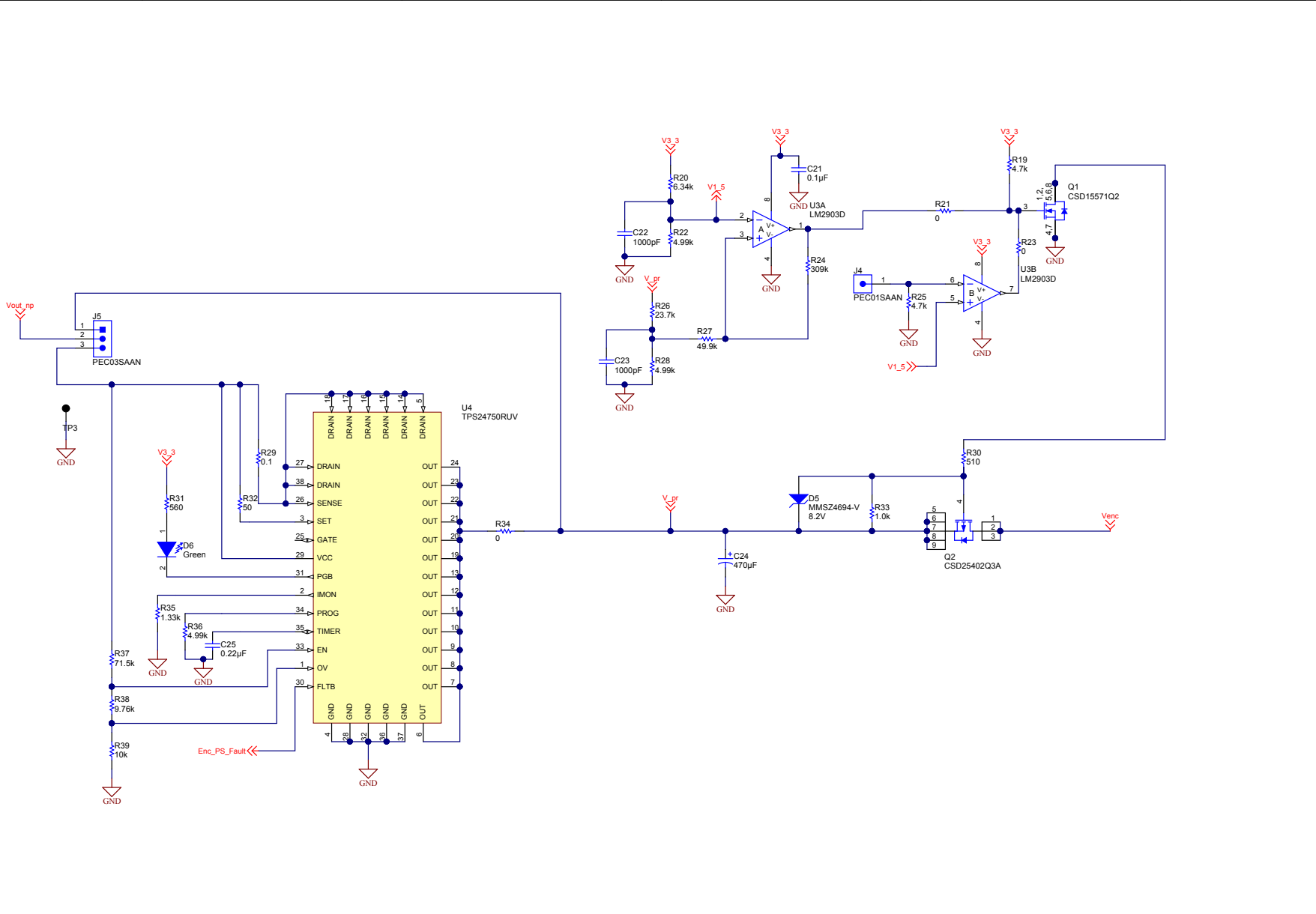
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TID #: 00117	Project Title: Interface to Hipurface DSL	
Number: TIDA-00177	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: TIDA-00177_production	Sheet: 1 of 4
Drawn By:	File: TIDA-00177_BD_SchDoc	Size: B
Engineer: Staebler/Stauder/Pizzolani	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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TID #: 00177	Project Title: Interface to Hiperface DSL		
Number: TIDA-00177   Rev: E1	Sheet Title:		
SVN Rev: Version control disabled	Assembly Variant: TIDA-00177 production	Sheet: 2 of 4	
Drawn By:	File: TIDA-00177_PS_SchDoc	Size: B	
Engineer: Staebler/Stauder/Pizzolan	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		© Texas Instruments 2015



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TID #: 001177	Project Title: Interface to Hiperface DSL	
Number: TIDA-001177   Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: TIDA-001177 production	Sheet: 3 of 4
Drawn By:	File: TIDA-001177_PR_SchDoc	Size: B
Engineer: Staebler/Stauder/Pizzolan	Contact: http://www.ti.com/support	





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